

## **ES3A thru ES3J**

# SURFACE MOUNT SUPER FAST RECTIFIERS

REVERSE VOLTAGE - **50** to **400** Volts FORWARD CURRENT - **3.0** Amperes

#### **FEATURES**

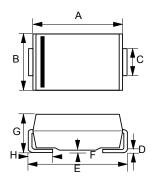
- Glass passivated chip
- Super fast switching for high efficiency
- For surface mounted applications
- Low forward voltage drop and high current capability
- Low reverse leakage current
- Plastic material has UL flammability classification 94V-0

#### **MECHANICAL DATA**

• Case : Molded plastic

Polarity: Color band denotes cathodeWeight: 0.007 ounces, 0.21 grams

### SMC



SMC						
DIM.	MIN.	MAX.				
Α	6.60	7.11				
В	5.59	6.22				
С	2.92	3.18				
D	0.15	0.31				
Е	7.75	8.13				
F	0.05	0.20				
G	2.01	2.50				
Н	0.76	1.52				
All Dimensions in millimeter						

#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

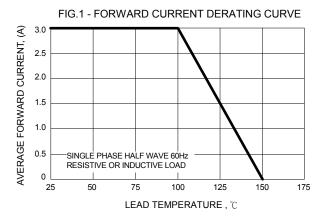
CHARACTERISTICS	SYMBOL	ES3A	ES3B	ES3C	ES3D	ES3G	ES3J	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	150	200	400	600	V
Maximum RMS Voltage	VRMS	35	70	105	140	280	420	V
Maximum DC Blocking Voltage	VDC	50	100	150	200	400	600	٧
Maximum Average Forward @TL =110°C	I(AV)	3.0						Α
Peak Forward Surge Current 8.3ms single half sine-wave super imposed on rated load	IFSM	100						А
Peak Forward Surge Current 1ms single half sine-wave @Tj=25°C	IFSM	200						А
$I^2 t \ \text{Rating for fusing (3ms} \! \leq \! t \leq \! 8.3 \text{ms)}$	I <sup>2</sup> t	41.5					A <sup>2</sup> S	
Maximum forward Voltage at 3.0A DC	VF	0.92 1.25				1.30	٧	
Maximum DC Reverse Current @TJ =25 ℃ at Rated DC Blocking Voltage @TJ=125 ℃	lR	10 500						uA
Maximum Reverse Recovery Time (Note 1)	TRR						35 30 (Typ.)	ns
Typical Junction Capacitance (Note 2)	Cı	45					pF	
Typical Thermal Resistance (Note 3)	Re JL	10 15					°C/W	
	Re JA	50					°C/W	
Operating Temperature Range	TJ	-55 to + 150					$^{\circ}\!\mathbb{C}$	
Storage Temperature Range	Тѕтс	-55 to + 150					$^{\circ}$	

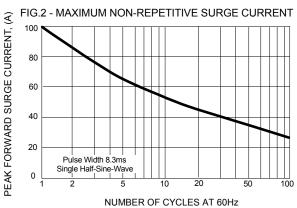
NOTES: 1. Reverse Recovery Test Conditions: IF=0.5A,IR=1.0A,IRR=0.25A.

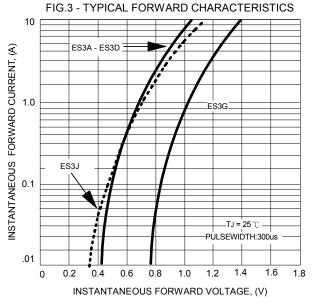
- 2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
- 3. Thermal Resistance junction to Lead and Ambient.

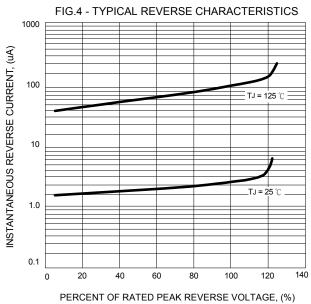
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